M16C/63, 64, 64A, 64C, 65, 65C, 6C, 5LD, 56D, 5L, 56, 5M, and 57 Groups

Use of User Boot Function

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1. Abstract

This document describes the method for rewriting the MCU internal flash memory (data flash, program ROM 1) using the user boot function in M16C/63, 64, 64A, 64C, 65 (products with 512 KB or less of program ROM 1 only), 65C, 6C, 5LD, 56D, 5L, 56, 5M, and 57 Group products.
The user boot function is for rewriting the MCU internal flash memory with a user-selected communication method.
(The user boot function is not the start up function of the user application program.)
This application note describes the user boot function using the M16C/64 Group.

2. Introduction

The application example described in this document applies to the following MCUs:

MCUs: M16/63, 64, 64A, 64C, 65 (products with 512 KB or less of program ROM 1 only)(1),
65C, 6C, 5LD, 56D, 5L, 56, 5M, 57 Groups
Oscillation frequency: 8 MHz
Operation frequency: 24 MHz (8 MHz in CPU rewrite mode)

Note:
1. MCUs with more than 512 KB of program ROM 1 have different software commands. Refer to the hardware manual for details.

Careful evaluation is recommended before using the program described in this application note.

3. Application

3.1 Outline

In this application note, control rewriting the MCU flash memory using serial communication from the host PC. Xmodem is used to transmit the MOTOROLA-S format. This application note introduces the following three methods regarding rewrite operation: normal programming, erase ignoring the lock bit status, and erase not ignoring the lock bit status.

3.2 Introduction of User Boot Function

M16C/63, 64, 64A, 64C, 65 (products with 512 KB or less of program ROM 1 only), 65C, 6C, 5LD, 56D, 5L, 56, 5M, and 57 Group products have the user boot function in boot mode. When the MCU starts in boot mode (operated after hardware reset occurs while a low-level signal is applied to the P5_5 pin and a high-level signal is applied to pins CNVSS and P5_0), user boot mode or standard serial I/O mode can be selected in accordance with the content of the user boot code area.
In user boot mode, the program written into the program ROM 2 area (starts from 10000h) on flash memory is executed.

The features of flash memory rewrite operation in user boot mode are described below.

- Ports (pins) for entry are freely selectable
  UART1 is used in standard serial I/O mode.
- Serial programmer(1) is freely selectable
  Protocols including communication method, contents of transmit/receive data (command, program code), and communication timing can be designed.

Note:

1. In standard serial I/O mode, a serial programmer supporting M16C/63, 64, 64A, 64C, 65, 65C, 6C, 5LD, 56D, 5L, 56, 5M, and 57 Groups is necessary.

3.3 Memory Map of Program ROM 2

Figure 3.1 shows the user boot program area and the user boot code area in program ROM 2.

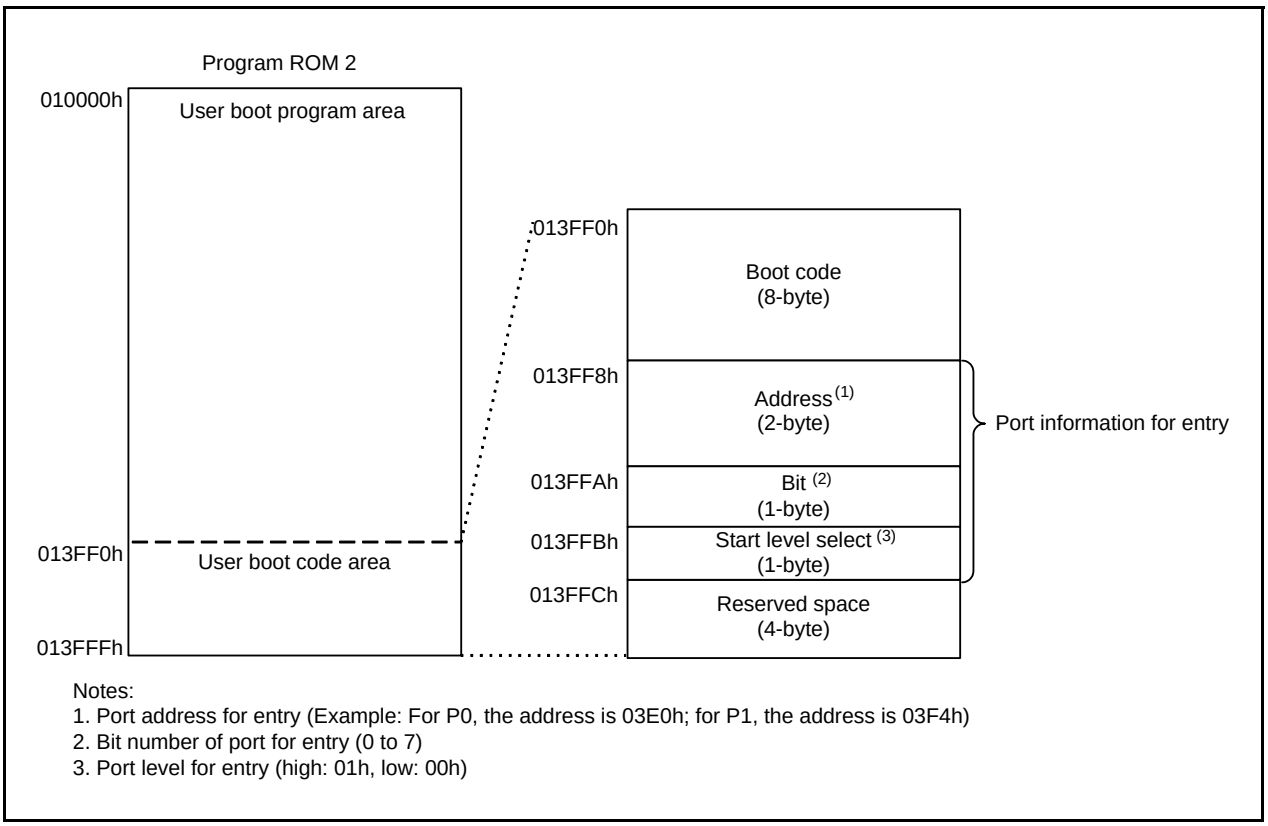


Figure 3.1 The User Boot Program Area and The User Boot Code Area

3.4 Set Values in the User Boot Code Area and Start Mode

Set values in the user boot code area and the corresponding start mode are described below where port Pi_j (i = 0 to 10, j = 0 to 7) is selected for entry. Table 3.1 lists Set Values in the User Boot Code Area and Start Mode. Only use the values listed in Table 3.1.

Table 3.1 Set Values in the User Boot Code Area and Start Mode

Boot Code (13FF0h to 13FF7h)	Port Information for Entry			Port Pi_j Input Level	Start Mode
	Address (13FF8h to 13FF9h)	Bit (13FFAh)	Start level select (13FFBh)		
"UserBoot"(1)	00000000h			—	User boot mode
	Pi register address(2)	00h to 07h (value of j)	00h	High	Standard serial I/O mode
				Low	User boot mode
			01h	High	User boot mode
				Low	Standard serial I/O mode
Other than "UserBoot"	—	—	—	—	Standard serial I/O mode

Notes:
1. See Table 3.2 "UserBoot" in ASCII Code.
2. See Table 3.3 Addresses of Selectable Ports for Entry.

Table 3.2 "UserBoot" in ASCII Code

Address	13FF0h	13FF1h	13FF2h	13FF3h	13FF4h	13FF5h	13FF6h	13FF7h
ASCII Code	55h (upper-case U)	73h (lower-case s)	65h (lower-case e)	72h (lower-case r)	42h (upper-case B)	6Fh (lower-case o)	6Fh (lower-case o)	74h (lower-case t)

Table 3.3 Addresses of Selectable Ports for Entry

Port	Pi Register Address
P0	03E0h
P1	03E1h
P2	03E4h
P3	03E5h
P4	03E8h
P5(1)	03E9h
P6	03ECh
P7	03EDh
P8	03F0h
P9	03F1h
P10	03F4h

Note:
1. The user boot mode is always selected as start mode if "UserBoot" is set to boot code while in either of the following conditions:
   • P5_0 is selected as a port information for entry and high level is selected as start level.
   • P5_5 is selected as a port information for entry and low level is selected as start level.

3.4.1 Configuration Example for User Boot Code Area

The user boot code area is set as ROMDATA of user boot program.

Configuration example for user boot code area on the following conditions:
Section name is "ubtcd_sec".
Port P10 (P10) is selected as a port for entry.
Bit 0 (P10_0) is selected as a bit for entry.
High is selected as start level.

<Section definition>
- When section address is specified in assembly language

```
;-----------------------------------------------------------------
;       User boot code area section
;-----------------------------------------------------------------
                .section        ubtcd_sec, ROMDATA
                .org            013FF0H
                .section        ubtcd_sec_FE, ROMDATA, ALIGN
```

- When section address is specified in the linkage editor (ln30)
  Add "-ORDER ubtcd_sec_FE=13FF0" to the command option in ln30.

<User boot code area definition >

```
/*-----------------------------------------------------------------------------------------*/
/*              define of "User boot code area"
/*-----------------------------------------------------------------------------------------*/
typedef struct UBTCD_DEF {
                unsigned char   btcd[8];                /* Boot-code */
                unsigned short  eptaddr;                /* SFR address of entry port */
                unsigned char   eptbitn;                /* Bit of the entry port */
                unsigned char   exptlvl;                /* Enable port level */
                unsigned long   ubtrsv;                 /* Reserved area */
} ubtcd_def;
#pragma SECTION rom ubtcd_sec           /* The section name "rom" is changed to "ubtcd_sec".  */
const far ubtcd_def UserBootCode = {{'U','s','e','r','B','o','o','t'},          /* Boot-code       = "UserBoot" */
 0x03F4,                                                                        /* Entry port      = "P10" */
 0x00,                                                                          /* Entry port bit  = bit0 */
 0x01,                                                                          /* Enable port level = "H" */
 0xFFFFFFFF                                                                     /* Reserved area */
 };
#pragma SECTION rom rom                 /* The section name is returned to "rom".  */
```

3.5 Notes on User Boot Program

User boot program code should fit in the program ROM 2 area. Also, start address of execution is 10000h in user boot mode.

When a user boot program is debugged using an on-chip debugger, set the reset vector value to 10000h and then turn on in single-chip mode.

Also, do not erase the block including the reset vector.

3.5.1 Rewriting Flash Memory

To rewrite the flash memory (data flash, program ROM 1), both EW0 mode and the EW1 mode of CPU rewrite mode can be used.

Table 3.4 lists the Limitations on Rewriting Flash Memory and Handling Procedure. Figure 3.2 shows the Relocation of User Boot Program, Figure 3.3 shows the Overview of Flash Memory Rewrite Operation.

Table 3.4 Limitations on Rewriting Flash Memory and Handling Procedure

Limitations	Handling Procedure
Flash memory can be erased on a block-by-block basis. (Flash memory has a finite number of program and erase cycles.)	Consider decreasing block erase cycles in block units when programming the flash memory.

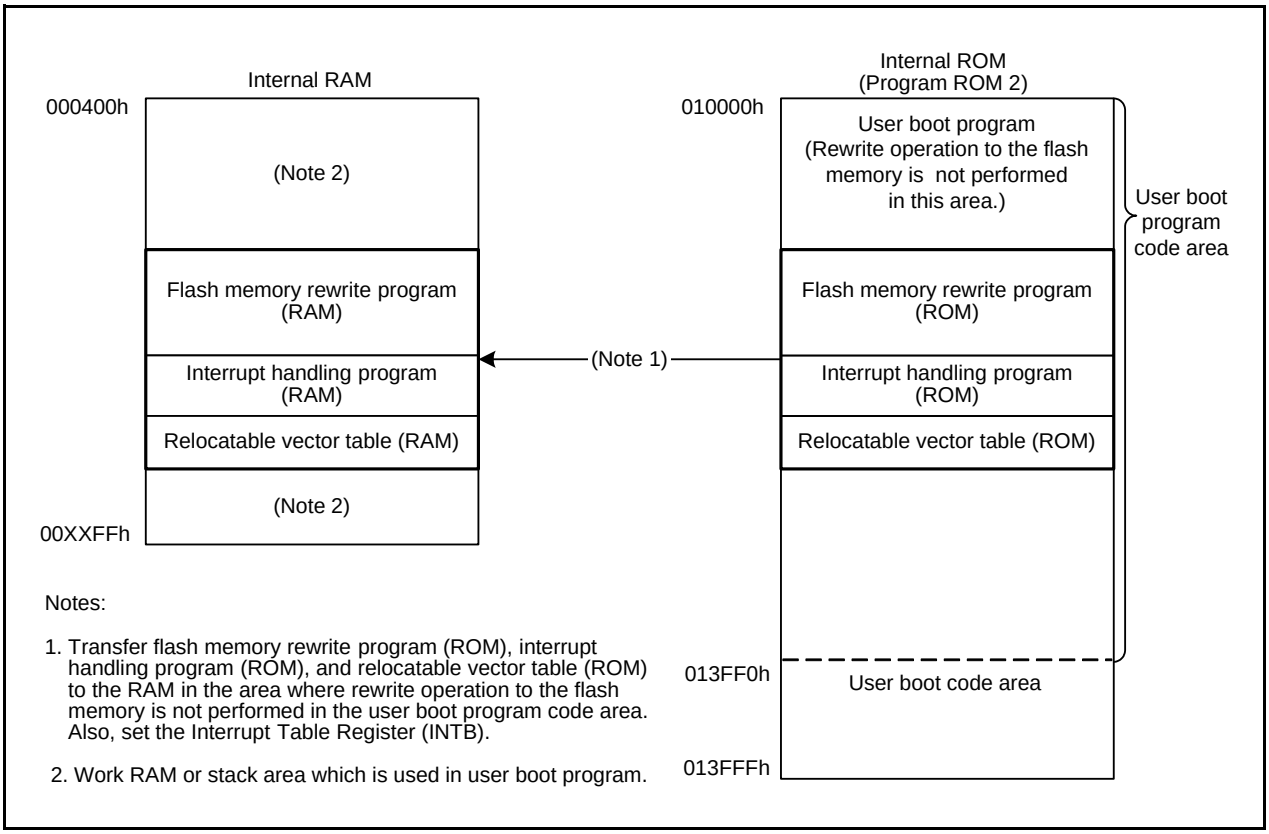


Figure 3.2 Relocation of User Boot Program

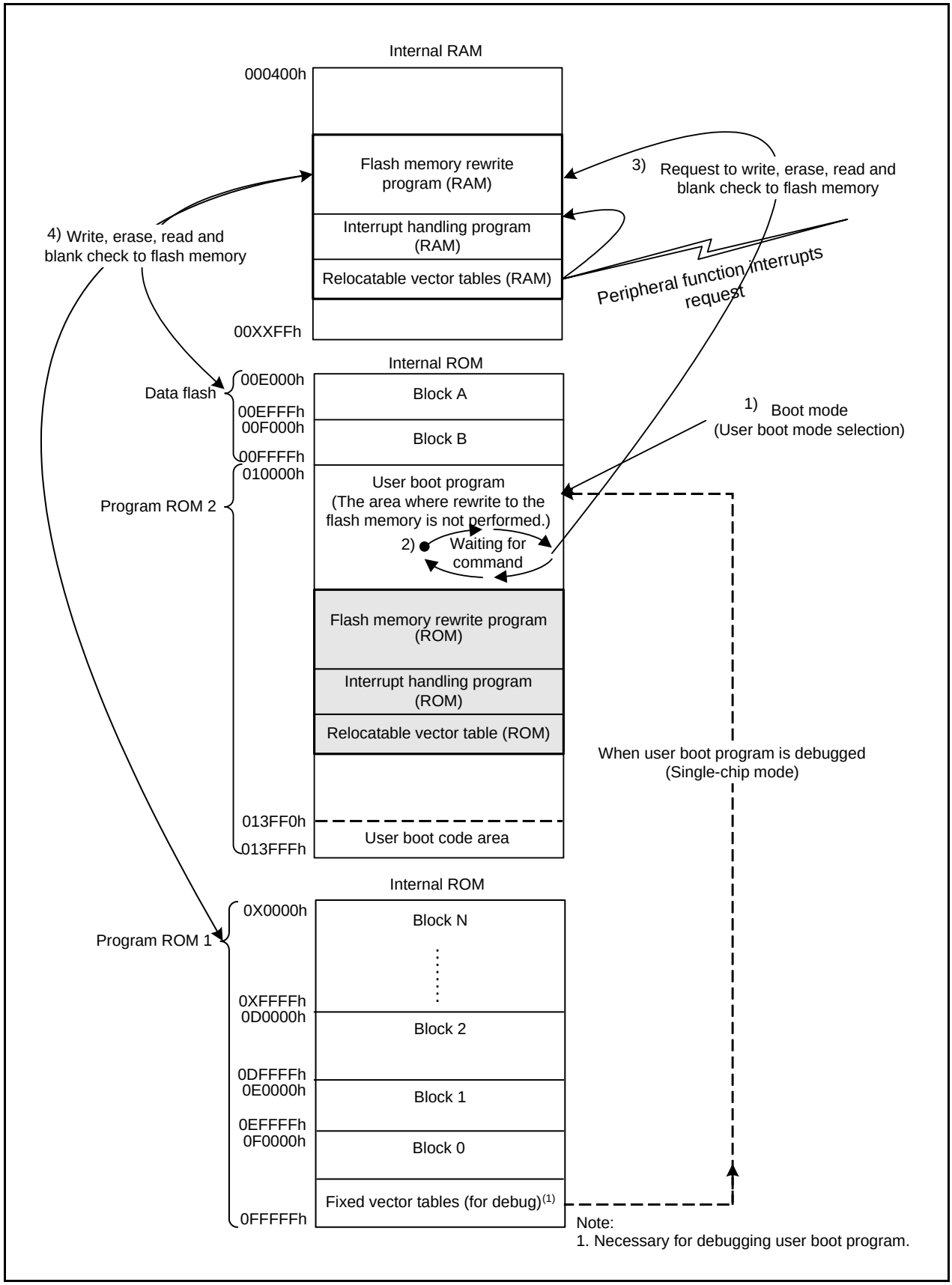


Figure 3.3 Overview of Flash Memory Rewrite Operation

3.5.2 Operating Speed of User Boot Program

Set a CPU clock frequency of 10 MHz or less when in CPU rewrite mode. Also, set the PM17 bit in the PM1 register to 1 (wait state) when internal RAM or internal ROM is accessed.

3.5.3 MCU Status When User Boot Mode is Selected

The value in the SFR is a value after reset and the value in the internal RAM is undefined. (Also, a value in the internal RAM is undefined after software reset.) Figure 3.4 shows the CPU Register Status When User Boot is Selected.

Table 3.5 SFR which Changes Is Status after CPU Reset or when User Boot Mode is Selected

Address	Register	Symbol	Reset Value	Value when User Boot Mode is Selected
0220h	Flash Memory Control Register 0	FMR0	0000 0001b	0010 0001b(1)

Note:
1. Set bit 5 to 1 to operate the FMR0 resister.

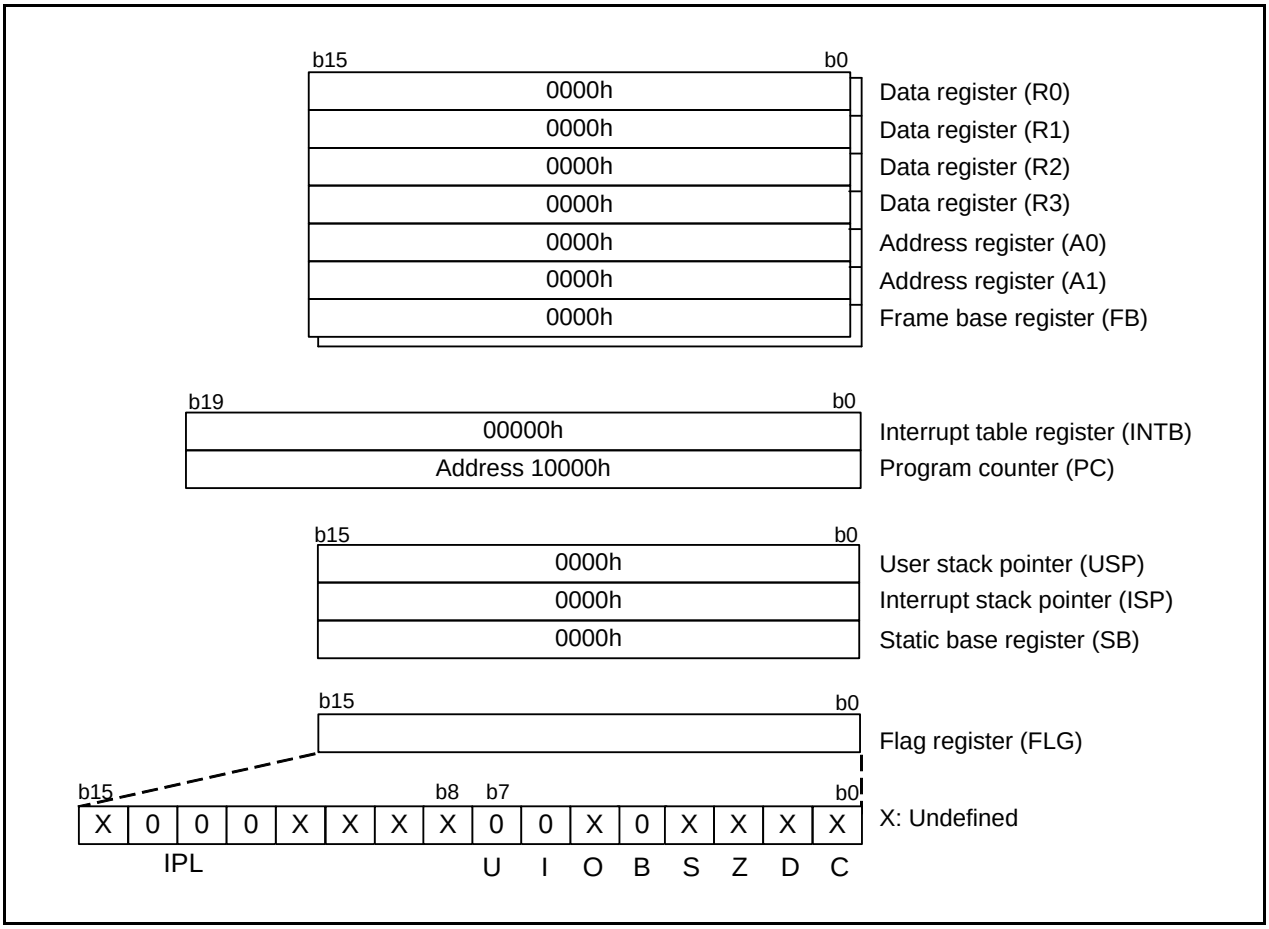


Figure 3.4 CPU Register Status When User Boot is Selected

3.5.4 Refreshing Watchdog Timer

When starting watchdog timer, for example, when WDTON bit in the OSF1 (address FFFFh) in the program ROM 1 is 0 (watchdog timer starts automatically after reset), refresh the watchdog timer in the user boot program.

3.6 Processing of User Boot Mode Selection

Figure 3.5 shows the Processing of User Boot Mode Selection.

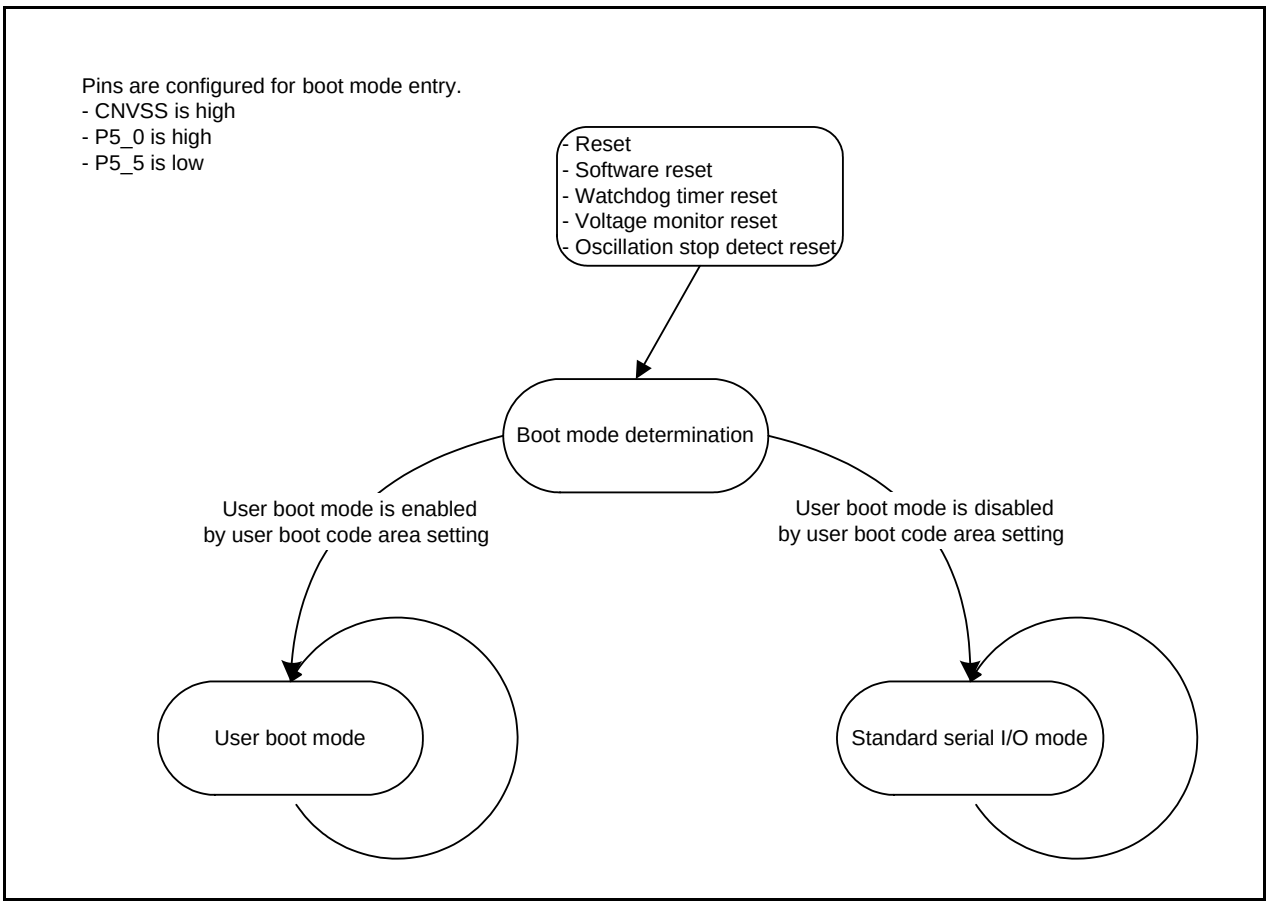


Figure 3.5 Processing of User Boot Mode Selection

4. Sample User Boot Programs

4.1 Overview

Program the internal flash memory using CPU rewrite mode (EW0 mode) and the user boot function in M16C/63, 64, 64A, 64C, 65 (products with 512 KB or less of program ROM 1 only), 65C, 6C, 5LD, 56D, 5L, 56, 5M, and 57 Group products.

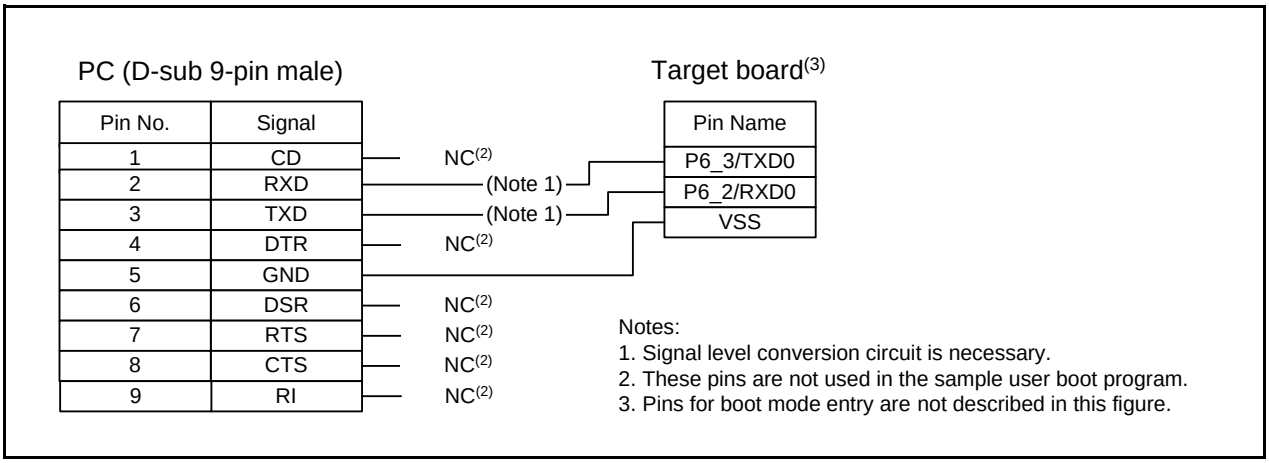
Programming targets
- Data flash (blocks A and B)
- Program ROM 1

Processing for the flash memory is transferred using a terminal software(1) running on a host PC.
Data written to the internal flash memory is MOTOROLA-S formatted text data and is transferred using XMODEM protocol(2).
The received MOTOROLA-S formatted data is converted to binary data and then written to the internal flash memory.

Notes:
1. The communication settings in the terminal software are as follows:
   Bits per second: 115200
   Data length: 8 bits
   Parity: None
   Stop bit: 1
   Flow control: None
2. Only the S1 record (16-bit address length) and S2 record (24-bit address length) are processed as data to program.

4.2 Connecting to the Host PC

A target MCU board and a host PC are connected with an RS-232C cable.



4.2.1 Pins Used

Table 4.1 Pins Used and Their Functions

Item	Pin Name	I/O	Power Supply	Remark
Power supply	VCC1	Input	—	Supply voltage
	VCC2	Input	—	Supply voltage
	VSS	Input	—	0 V input
Reset input	$\overline{\text{RESET}}$	Input	VCC1	—
CNVSS	CNVSS	Input	VCC1	VCC1 input(1)
Bus control pins	P5_0($\overline{\text{CE}}$) / $\overline{\text{WRL}}$ / $\overline{\text{WR}}$	Input	VCC2	VCC2 input(1)
	P5_5($\overline{\text{EPM}}$) / $\overline{\text{HOLD}}$	Input	VCC2	VSS input(1)
Serial interface UART0	P6_2 / RDX0 / SCL0	Input	VCC1	Serial data input
	P6_3 / TDX0 / SDA0	Output	VCC1	Serial data output
I/O port	P10_0	Input	VCC1	VCC1 input to select user boot mode(2)

Notes:
1. Setting for boot mode entry.
2. Set value in the sample user boot program. Refer to Table 3.3 Addresses of Selectable Ports for Entry for details.

4.3 Processing Outline

Table 4.2 lists the processing to be selected in the terminal software. Each processing has a timeout. If input is not made for a certain time, the processing command is canceled, and the command must be input from the beginning again.

Table 4.2 Processing

No.	Processing	Outline
1	Blank check	Perform a blank check on the internal flash memory in block units. The blank check can be performed on the data flash (blocks A and B) and program ROM 1 (blocks 0 to 3).
2	Erase	Erase the internal flash memory when the lock bit is disabled (unlocked). Erase can be performed on the data flash (blocks A and B) and program ROM 1 (blocks 0 to 3).
3	Erase of selection block	Erase a selected block of the internal flash memory when the lock bit is disabled (unlocked). Erase for a selected block can be performed on the data flash (blocks A and B) and program ROM 1 (blocks 0 to 3).
4	Program of transferred file	Program MOTOROLA-S formatted data(1) to the internal flash memory communicating through XMODEM protocol.
5	Checksum calculation and CRC calculation	Calculate the checksum and CRC for the data flash (8 KB of blocks A and B) and program ROM 1 (256 KB of blocks 0 to 3), respectively.
6	Lock setting of lock bit	Enable the lock bit (locked) for the internal flash memory in block units. This operation is applicable for the data flash (blocks A and B) and program ROM 1 (blocks 0 to 3).
7	Display of lock bit status	Read the lock bit status and display the read result in block units. This operation is applicable for the data flash (block A and B) and program ROM 1 (blocks 0 to 3).
8	Lock bit and erase for selected block	Erase the selected block regardless of its lock bit status. The lock bit of the erased block is disabled (unlocked).

Note:
1. Place the data in blocks A, B, and 0 to 3 only.

4.3.1 User Interface

This section describes the contents and selection value displayed on the host PC screen by terminal software communication.
Refer to the terminal software operating instructions for details on transmitting the MOTOROLA-S formatted file using the XMODEM communication protocol.

(1) Menu

Select a number from 1 to 8 which corresponds to the number shown in Table 4.2 Processing.
The menu is displayed again if a number other than 1 to 8 is entered.

Terminal software window

```
M16C/64 User Boot Menu  v2.00
------------------------------

1...Blank Check
2...Erase
3...Erase of selection block
4...Program Flash via XModem Download
5...Checksum calculation and CRC calculation
6...Lock of lock bit
7...Display of lock bit status
8...Unlock of lock bit and erase of selection block
>
```

(2) Blank check

When “1” is entered, blocks A, B, and 0 to 3 are checked to see if they are blank (no written data present). The checked result is displayed for each block.

Terminal software window

```
5...Checksum calculation and CRC calculation
6...Lock of lock bit
7...Display of lock bit status
8...Unlock of lock bit and erase of selection block

>1
Blank checking user area...
  Block-A is a blank.
  Block-B is a blank.
  Block-0 is a blank.
  Block-1 is not a blank.
  Block-2 is a blank.
  Block-3 is a blank.
Blank check is done.
```

When blocks are blank (no written data present)

When a block is not blank (written data present)

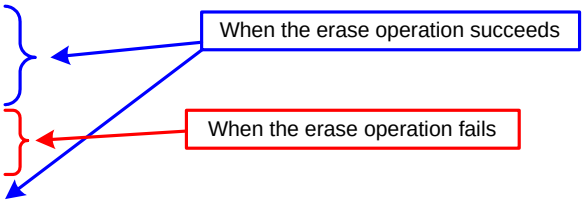
(3) Erase

When “2” is entered, the erase command is executed for blocks A, B, and 0 to 3 in the internal flash memory. The results of the erase operations are displayed for each block. The erase operation for blocks locked with the lock bit fails. For blocks that are not locked and are blank, the erase command is not executed and “Succeeded.” is displayed.

Terminal software window

```
5...Checksum calculation and CRC calculation
6...Lock of lock bit
7...Display of lock bit status
8...Unlock of lock bit and erase of selection block

>2
Really erase ALL user blocks (Y/N)?y
  Erasing of Block-A ... Succeeded.
  Erasing of Block-B ... Succeeded.
  Erasing of Block-0 ... Succeeded.
  Erasing of Block-1 ... Failed.
  Erasing of Block-2 ... Failed.
  Erasing of Block-3 ... Succeeded.
Erasing all blocks ended.
```

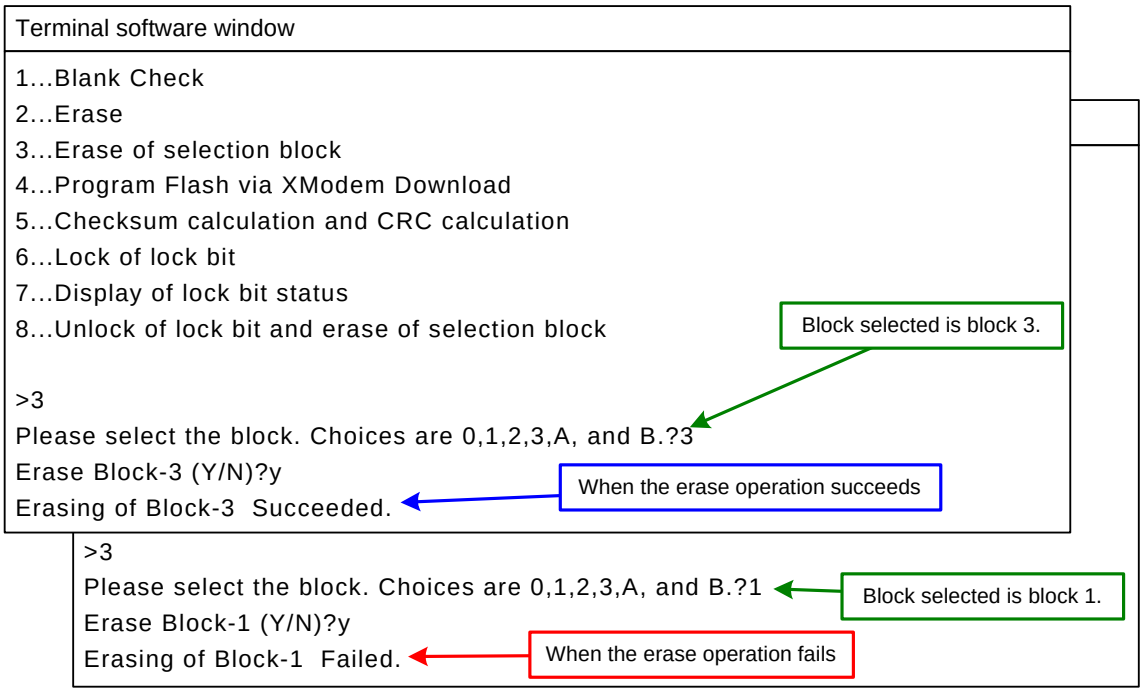


(4) Erase of selection block

When “3” is entered, one block selected from blocks A, B, and 0 to 3 of the internal flash memory is erased. The erase operation for the block locked with the lock bit fails. For a block which is not locked and is blank, the erase command is not executed and “Succeeded.” is displayed. Table 4.3 lists the Block Selection Key.

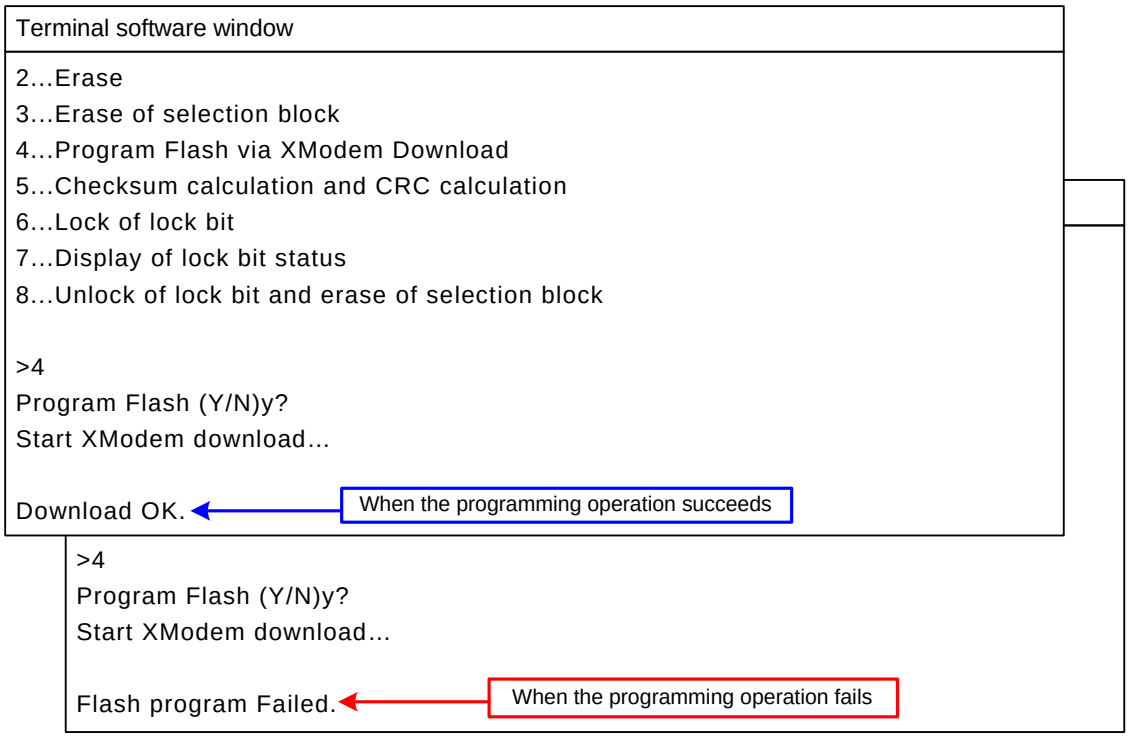
Table 4.3 Block Selection Key

Block Type	Block Name	Size	Address	Selection Key
Data flash	Block A	4 KB	E000h to EFFFh	A
	Block B	4 KB	F000h to FFFFh	B
Program ROM 1	Block 3	64 KB	C0000h to CFFFFh	3
	Block 2	64 KB	D0000h to DFFFFh	2
	Block 1	64 KB	E0000h to EFFFFh	1
	Block 0	64 KB	F0000h to FFFFFh	0



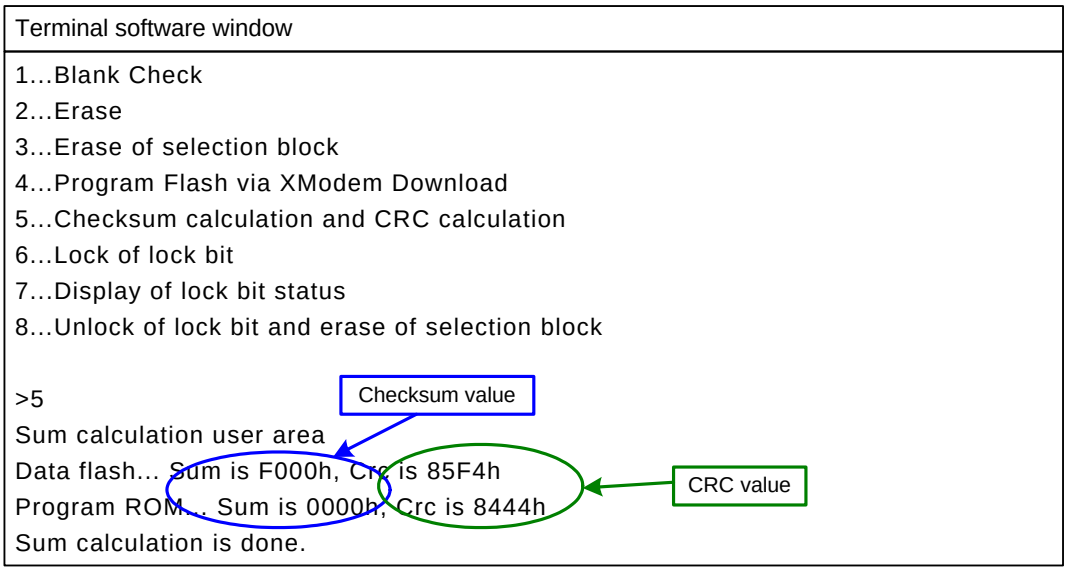
(5) Program transmit file

When “4” is entered, preparations are made to program the internal flash memory. Transmit the file for programming. Refer to the instructions of the terminal software for communication settings and transmit operation with the XMODEM protocol. When the internal flash memory to be programmed (blocks A, B, or 0 to 3) is locked with the lock bit or is not blank, the programming operation fails.



(6) Checksum calculation and CRC calculation

When “5” is entered, execute checksum and CRC calculation for blocks A, B, and 0 to 3 of the internal flash memory. The results of these operations are displayed in 2-byte units for the data flash (addresses E000h to FFFFh) and program ROM 1 (addresses C0000h to FFFFFh), respectively.



(7) Lock of lock bit

When “6” is entered, the lock bit program is executed for blocks A, B, and 0 to 3, and lock bits for these blocks are set to 0 (locked). The results of the lock bit program are displayed for each block. For a block whose lock bit is already 0, “Failed.” is displayed.

Terminal software window

```
5...Checksum calculation and CRC calculation
6...Lock of lock bit
7...Display of lock bit status
8...Unlock of lock bit and erase of selection block

>6
The lock bit is put into the state of the lock.
Lock of Block-A Failed.
Lock of Block-B Failed.
Lock of Block-0 Succeeded.
Lock of Block-1 Succeeded.
Lock of Block-2 Succeeded.
Lock of Block-3 Succeeded.
Block lock bit program is done.
```

When the lock bit program fails

When the lock bit program succeeds

(8) Display of lock bit status

When “7” is entered, the lock bit status of blocks A, B, and 0 to 3 of the internal flash are read. The read statuses are displayed for each block.

Terminal software window

```
5...Checksum calculation and CRC calculation
6...Lock of lock bit
7...Display of lock bit status
8...Unlock of lock bit and erase of selection block

>7
The state of the lock bit is displayed.
  Block-A is unlocked.
  Block-B is unlocked.
  Block-0 is locked.
  Block-1 is locked.
  Block-2 is locked.
  Block-3 is locked.
Read Block lock bit status is done.
```

When blocks are unlocked

When blocks are locked

(9) Unlock of lock bit and erase of selection block

When “8” is entered, the lock bit is disabled (unlocked) and the block selected from blocks A, B, and 0 to 3 of the internal flash memory is erased. In this operation, the lock bit status becomes 1 (unlocked). For a block which is not locked and is blank, the erase command is not executed and “Succeeded.” is displayed. Refer to Table 4.3 Block Selection Key for block selection.

Terminal software display

```
1...Blank Check
2...Erase
3...Erase of selection block
4...Program Flash via XModem Download
5...Checksum calculation and CRC calculation
6...Lock of lock bit
7...Display of lock bit status
8...Unlock of lock bit and erase of selection block

>8
Please select the block. Choices are 0,1,2,3,A, and B.?0
Unlock and erase Block-0 (Y/N)?y
Unlock and erasing of Block-0  Succeeded.
```

When the unlock and erase operations succeed

4.3.2 Usage Example

Figure 4.1 shows an example of rewriting the internal flash memory using the sample user boot program.

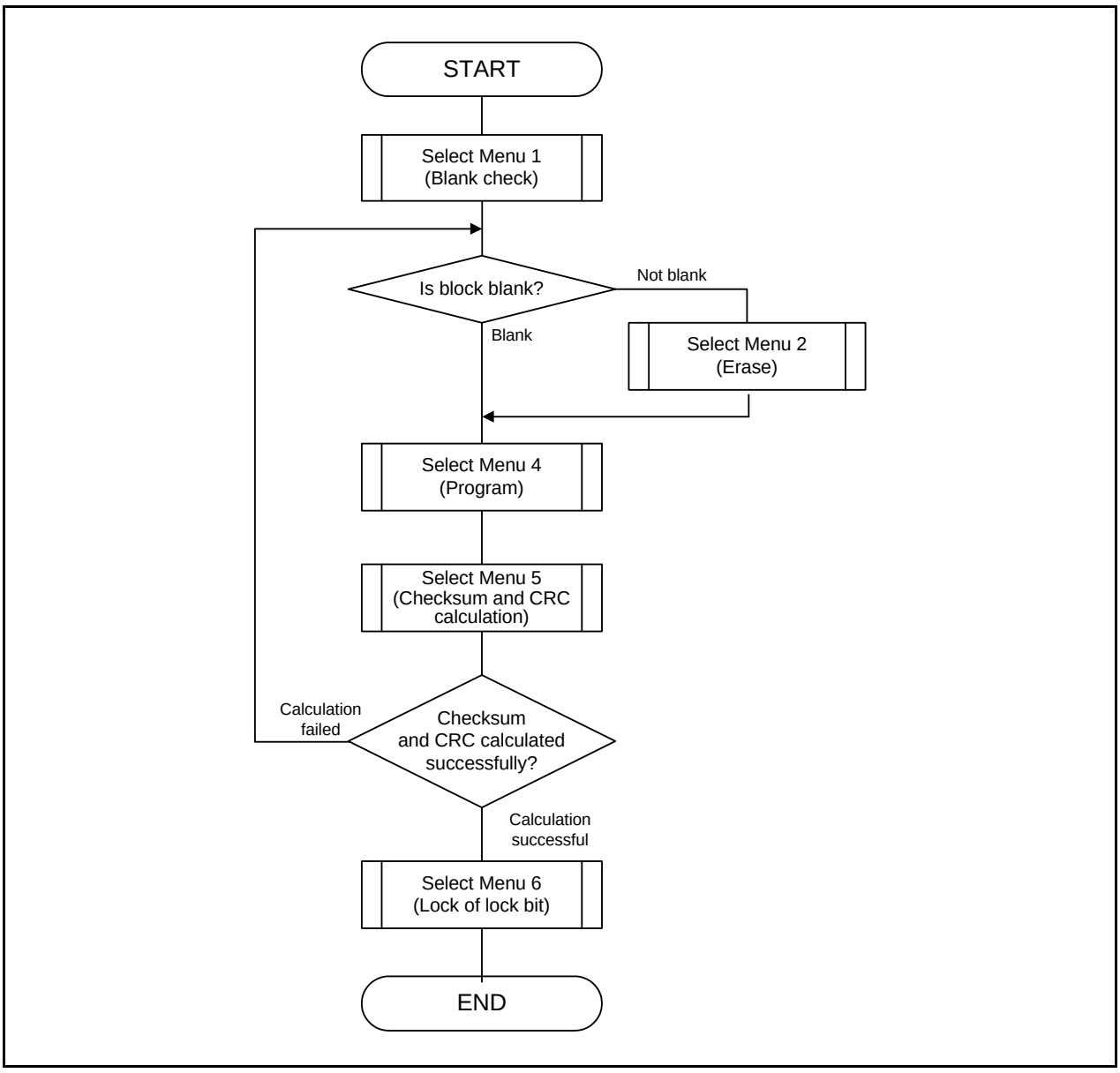


Figure 4.1 Sample User Boot Program

4.4 Program

4.4.1 File Composition

Table 4.4 lists the files used in the sample user boot program.

Table 4.4 Files Used in the Sample Program

File Name	Outline	Remarks
common.c	Common processing module	
common.h	Header file for external reference of common processing module	Type definition and prototype declaration of common function
lowlevelinit.c	MCU initialization module	
lowlevelinit.h	Header file for external reference of MCU initialization module	
int_dmy.c	Undefined interrupt (dummy) handling	
int_dmy.h	Prototype declaration of undefined interrupt handling	
flash_drv.c	Internal flash memory programming module in CPU rewrite mode (EW0 mode)	
flash_drv.h	Header file for external reference of internal flash memory rewriting module	
serial0_drv.c	Serial (UART0) data communication module	
serial0_drv.h	Header file for external reference of serial (UART0) data communication module	
timerA0_drv.c	Timer A0 (timer mode) control module	For measuring timeout period
timerA0_drv.h	Header file for external reference of timer A0 (timer mode) control module	
timerB5_drv.c	Timer B5 (timer mode) control module	For measuring watchdog timer refresh cycle
timerB5_drv.h	Header file for external reference of timer B5 (timer mode) control module	
wdtRefresh.h	Macro definition for refreshing watchdog timer	
xmodem.c	XMODEM protocol interface module	
xmodem.h	Header file for external reference of XMODEM protocol interface module	
flash_menu.c	User boot menu processing module	Usage example of sample source files
flash_menu.h	Header file for external reference of user boot menu processing module	
UserBoot.c	User boot main processing	The definition of user boot code area is included.
UserBoot.h	Definition of execution address in the RAM area	Definition of relocatable vector, interrupt handler, executable code in the RAM area, and data address in the RAM area

4.4.2 Internal Flash Memory Rewriting Module

Table 4.5 lists Module Interfaces in the internal flash memory rewriting module (flash_drv) of the sample user boot program, and Table 4.6 lists the definition of data type used in the sample program.

Table 4.5 Module Interfaces

Interface Name	Function	Remark
BLOCK_A_IDX	Block index number of internal flash memory (Block A of data flash)	FLASH_BLOCK_NUM type data
BLOCK_B_IDX	Block index number of internal flash memory (Block B of data flash)	FLASH_BLOCK_NUM type data
BLOCK_0_IDX	Block index number of internal flash memory (Block 0 of program ROM 1)	FLASH_BLOCK_NUM type data
BLOCK_1_IDX	Block index number of internal flash memory (Block 1 of program ROM 1)	FLASH_BLOCK_NUM type data
BLOCK_2_IDX	Block index number of internal flash memory (Block 2 of program ROM 1)	FLASH_BLOCK_NUM type data
BLOCK_3_IDX	Block index number of internal flash memory (Block 3 of program ROM 1)	FLASH_BLOCK_NUM type data
FDS_OK	Succeeded	FLASH_STATUS type data
FDS_NOT_BLANK	Not blank	FLASH_STATUS type data
FDS_BLOCK_LOCK	The block lock bit is 0 (locked).	FLASH_STATUS type data
FDS_BLOCK_UNLOCK	The block lock bit is 1 (unlocked).	FLASH_STATUS type data
FDS_LBP_FAIL	Lock bit program failed	FLASH_STATUS type data
FDS_PROG_FAIL	Program failed (A program error notice from the flash memory has been received.)	FLASH_STATUS type data
FDS_ADDR_ERROR	Write address error (Not 4-byte aligned)	FLASH_STATUS type data
FDS_ERASE_FAIL	Erase failed (An erasure error notice from the flash memory has been received.)	FLASH_STATUS type data
BLOCK_IDX_NUM	Number of blocks in flash memory	Total number of the blocks in data flash and program ROM 1
BLOCK_FIRST_IDX	Start index of the block definition in the flash memory	
LBP_DISABLE	Lock bit disabled	
LBP_ENABLE	Lock bit enabled	
InitFlashDrv	Internal flash memory rewriting module initialization	
ClearStatusRegister	Request for clearing the status register of internal flash memory	
BlankReadCheck	Blank check for the specified block (value read in flash memory is 0xFFFF)	
BlockBlankCheck	Request for blank (state after erase) check for the specified block	
BlockErase	Request for the auto-erase operation for the specified block	
Program128bytes	Request for the 128-byte continuous auto-program operation	
LockBitProgram	Request for enabling the lock bit of the specified block	
ReadLockBitStatus	Request for obtaining the lock bit status of the specified block	
FlashReadSumCalc	Calculation of checksum value and CRC-CCITT value for the specified block	

Table 4.6 Definition of Data Type

Data Type Name	Data Type	Definition Header
SBYTE	signed char	common.h
UBYTE	unsigned char	common.h
SWORD	signed short	common.h
UWORD	unsigned short	common.h
SDWORD	signed long	common.h
UDWORD	unsigned long	common.h
FLASH_BLOCK_NUM	enum	flash_drv.h
FLASH_STATUS	enum	flash_drv.h

Functions of flash memory rewriting module (flash_drv) used in the sample user boot program are described below.

Function	InitFlashDrv		
Outline	Initialization of the internal flash memory rewriting module		
External Reference	Interface Name	Content	Definition Header
	PRCR	SFR (Protect register)	sfr64.h
	PM10	SFR (Data flash enable bit)	sfr64.h
	memcpy	Standard function (Copy of memory area)	string.h
	WDT_INITIALIZE	Watchdog timer refresh	wdtRefresh.h
	RAM_DATA_ADDRESS	RAM address to which data copies	UserBoot.h
	RAM_BASED_ROM_DATA_ADDRESS	ROM address from which data copies	UserBoot.h
	SIZE_OF_RAM_BASED_ROM_DATA	Number of bytes of copied data	UserBoot.h
	RAM_PROG_ADDRESS	RAM address to which program code is copied	UserBoot.h
	RAM_BASED_ROM_PROG_ADDRESS	ROM address from which program code is copied	UserBoot.h
	SIZE_OF_RAM_BASED_ROM_PROG	Number of bytes of copied program code	UserBoot.h
Declaration	void InitFlashDrv (void);		
Argument	Type	Meaning	
	void	None	
Returned Value	Type	Meaning	
	void	None	
Function			
• Enable data flash (addresses 0E000h to 0FFFFh). • Copy the program code for handling the internal flash memory and data to the RAM area. • Execute watchdog timer refresh processing (refreshing watchdog timer).			
Remark			
This function must be executed (once) when the function of the internal flash memory rewriting module (flash_drv) is used.			

Function	ClearStatusRegister		
Outline	Request to clear the status register of internal flash memory		
External Reference	Interface Name	Content	Definition Header
	FMR00	SFR (RY/BY status flag)	sfr64.h
	FMR06	SFR (Program status flag)	sfr64.h
	FMR07	SFR (Erase status flag)	sfr64.h
Declaration	void ClearStatusRegister (void);		
Argument	Type	Meaning	
	void	None	
Returned Value	Type	Meaning	
	void	None	
Function			
• Enter CPU rewrite mode (EW0 mode) and execute the software command (clear status register) in the internal flash memory. • Exit CPU rewrite mode (EW0 mode) after verifying the status register is cleared.			
Remark			
Exit this function when the internal flash memory is ready (FMR00 is 1), program status is normal (FMR06 is 0), and the erase status is normal (FMR07 is 0). Interrupts are disabled (I flag is cleared) while in CPU rewrite mode (EW0 mode).			

Function	BlankReadCheck		
Outline	Blank check of a specified block (value read in flash memory is 0xFFFF)		
External Reference	Interface Name	Content	Definition Header
	None	None	None
Declaration	FLASH_STATUS BlankReadCheck (FLASH_BLOCK_NUM BlockNum, UWORD *Data);		
Argument	Type	Meaning	
	FLASH_BLOCK_NUM	The block index number for blank check in the internal flash memory (value read in flash memory is 0xFFFF)	
	UWORD *	Value read in flash memory when the block is not blank	
Returned Value	Type	Meaning	
	FLASH_STATUS	FDS_OK: Blank FDS_NOT_BLANK: Not blank	
Function			
• Return FDS_OK (blank) when the data of all specified block areas in the internal flash memory is 0xFFFF. • Store the read value in the argument *Data when the data of the specified block areas is not 0xFFFF, and return FDS_NOT_BLANK (not blank).			
Remark			
None			

<table>
<tr><td>Function</td><td colspan="3">BlockBlankCheck</td></tr>
<tr><td>Outline</td><td colspan="3">Request to blank check (state after erase) the specified block</td></tr>
<tr><td rowspan="3">External Reference</td><td>Interface Name</td><td>Content</td><td>Definition Header</td></tr>
<tr><td>FMR00</td><td>SFR (RY/BY status flag)</td><td>sfr64.h</td></tr>
<tr><td>FMR07</td><td>SFR (Erase status flag)</td><td>sfr64.h</td></tr>
<tr><td>Declaration</td><td colspan="3">FLASH_STATUS BlockBlankCheck (FLASH_BLOCK_NUM BlockNum);</td></tr>
<tr><td rowspan="2">Argument</td><td>Type</td><td colspan="2">Meaning</td></tr>
<tr><td>FLASH_BLOCK_NUM</td><td colspan="2">The block index number of the specified block for blank check (state after erase) in the internal flash memory</td></tr>
<tr><td rowspan="2">Returned Value</td><td>Type</td><td colspan="2">Meaning</td></tr>
<tr><td>FLASH_STATUS</td><td colspan="2">FDS_OK: Blank
FDS_NOT_BLANK: Not blank</td></tr>
<tr><td colspan="4">Function</td></tr>
<tr><td colspan="4">• Enter CPU rewrite mode (EW0 mode) and execute the software command (block blank check) in the internal flash memory.
• Determine the returned value depending on the erase status flag (FMR07) and exit CPU rewrite mode (EW0 mode).
a) Return FDS_OK (blank) when the erase status flag is normal (FMR07 is 0).
b) Return FDS_NOT_BLANK (not blank) when the erase status flag is in error (FMR07 is 1).</td></tr>
<tr><td colspan="4">Remark</td></tr>
<tr><td colspan="4">The software command (clear status register) is executed when the returned value is FDS_NOT_BLANK. Exit this function when the erase status becomes normal (FMR07 is 0) in the internal flash memory.
Interrupts are disabled (I flag is cleared) while in CPU rewrite mode (EW0 mode).</td></tr>
</table>

<table>
<tr><td>Function</td><td colspan="3">BlockErase</td></tr>
<tr><td>Outline</td><td colspan="3">Request for the auto-erase operation for the specified block</td></tr>
<tr><td rowspan="4">External Reference</td><td>Interface Name</td><td>Content</td><td>Definition Header</td></tr>
<tr><td>FMR00</td><td>SFR (RY/BY status flag)</td><td>sfr64.h</td></tr>
<tr><td>FMR07</td><td>SFR (Erase status flag)</td><td>sfr64.h</td></tr>
<tr><td>WDT_INITIALIZE</td><td>Refreshing watchdog timer</td><td>wdtRefresh.h</td></tr>
<tr><td>Declaration</td><td colspan="3">FLASH_STATUS BlockErase (FLASH_BLOCK_NUM BlockNum, UWORD LBPEnableFlag);</td></tr>
<tr><td rowspan="3">Argument</td><td>Type</td><td colspan="2">Meaning</td></tr>
<tr><td>FLASH_BLOCK_NUM</td><td colspan="2">The block index number for the auto-erase operation in the internal flash memory</td></tr>
<tr><td>UWORD LBPEnableFlag</td><td colspan="2">LBP_ENABLE: Lock bit enabled (FMR02 is 0)
LBP_DISABLE: Lock bit disabled (FMR02 is 1)</td></tr>
<tr><td rowspan="2">Returned Value</td><td>Type</td><td colspan="2">Meaning</td></tr>
<tr><td>FLASH_STATUS</td><td colspan="2">FDS_OK: Erase succeeded
FDS_ERASE_FAIL: Erase failed</td></tr>
<tr><td colspan="4">Function</td></tr>
<tr><td colspan="4">When the specified block is not blank or is locked while LBPEnableFlag is LBP_ENABLE (lock bit enabled), the erase command is executed for the block.
When the block is blank and not locked, the erase command is not executed and FDS_OK (erase succeeded) is returned.
When the specified block is not blank or is locked while LBPEnableFlag is LBP_DISABLE (lock bit disabled), the lock bit is disabled and the erase command is executed for the block.
When the block is blank and not locked, the erase command is not executed and FDS_OK (erase succeeded) is returned.
When an erase error or an illegal command error occurs, FDS_ERASE_FAIL (erase failed) is returned as the returned value.
When the erase operation succeeds, FDS_OK (erase succeeded) is returned.</td></tr>
<tr><td colspan="4">Remark</td></tr>
<tr><td colspan="4">The watchdog timer is refreshed during the auto-erase operation (FMR00 is 0) in internal flash memory.
Interrupts are disabled (I flag is cleared) in CPU rewrite mode (EW0 mode).</td></tr>
</table>

Function	Program128bytes		
Outline	Request for 128-byte continuous auto-program operation		
External Reference	Interface Name	Content	Definition Header
	FMR00	SFR (RY/BY status flag)	sfr64.h
	FMR06	SFR (Program status flag)	sfr64.h
Declaration	FLASH_STATUS Program128bytes (UDWORD Address, UWORD *Data);		
Argument	Type	Meaning	
	UDWORD	Start address to program in the internal flash memory	
	UWORD *	Buffer pointer for storing data to be programmed (128 bytes)	
Returned Value	Type	Meaning	
	FLASH_STATUS	FDS_OK: Program succeeded FDS_PROG_FAIL: Program failed FDS_ADDR_ERROR: Write address error	
Function			
• When the start address for programming (UDWORD Address) is not 4-byte aligned, set FDS_ADDR_ERROR (write address error) as the returned value and terminate the operation. • When the start address for programming (UDWORD Address) is 4-byte aligned, enter CPU rewrite mode (EW0 mode) and execute the software command (program) for 128-byte data in the internal flash memory. • Determine the returned value depending on the program status flag (FMR06) and exit CPU rewrite mode (EW0 mode). a) Return FDS_OK (program succeeded) when the program status flag is normal (FMR06 is 0). b) Return FDS_PROG_FAIL (program failed) when program status flag is in error (FMR06 is 1).			
Remark			
Interrupts are disabled (I flag is cleared) while in CPU rewrite mode (EW0 mode).			

Function	LockBitProgram		
Outline	Request to enable the lock bit of the specified block		
External Reference	Interface Name	Content	Definition Header
	FMR00	SFR (RY/BY status flag)	sfr64.h
	FMR06	SFR (Program status flag)	sfr64.h
Declaration	FLASH_STATUS LockBitProgram (FLASH_BLOCK_NUM BlockNum);		
Argument	Type	Meaning	
	FLASH_BLOCK_NUM	The block index number of the specified block for the lock bit program in the internal flash memory	
Returned Value	Type	Meaning	
	FLASH_STATUS	FDS_OK: Lock bit program succeeded FDS_LBP_FAIL: Lock bit program failed	
Function			
• Enter CPU rewrite mode (EW0 mode) and execute the software command (lock bit program) in the internal flash memory. • Determine the returned value depending on the program status flag (FMR06) and exit CPU rewrite mode (EW0 mode). a) Return FDS_OK (lock bit program succeeded) when program status flag is normal (FMR06 is 0). b) Return FDS_LBP_FAIL (lock bit program failed) when program status flag is in error (FMR06 is 1).			
Remark			
Interrupts are disabled (I flag is cleared) in CPU rewrite mode (EW0 mode).			

Name	ReadLockBitStatus		
Outline	Request to obtain the lock bit status of the specified block		
External Reference	Interface Name	Content	Definition Header
	FMR00	SFR (RY/BY status flag)	sfr64.h
	FMR16	SFR (Lock bit status flag)	sfr64.h
Declaration	FLASH_STATUS ReadLockBitStatus (FLASH_BLOCK_NUM BlockNum);		
Argument	Type	Meaning	
	FLASH_BLOCK_NUM	The block index number for obtaining the lock bit status in the internal flash memory	
Returned Value	Type	Meaning	
	FLASH_STATUS	FDS_BLOCK_LOCK: The lock bit status is 0 (locked) FDS_BLOCK_UNLOCK: The lock bit status is 1 (unlocked)	
Function			
• Enter CPU rewrite mode (EW0 mode) and execute the software command (read lock bit status) in the internal flash memory. • Determine the returned value depending on the lock bit status (FMR16) and exit CPU rewrite mode (EW0 mode). a) Return FDS_BLOCK_LOCK (locked) when the lock bit status is normal (FMR16 is 0). b) Return FDS_BLOCK_UNLOCK (unlocked) when the lock bit status is in error (FMR16 is 1).			
Remark			
Interrupts are disabled (I flag is cleared) while in CPU rewrite mode (EW0 mode).			

Name	FlashReadSumCalc		
Outline	Calculation of checksum value and CRC-CCITT value for the specified block		
External Reference	Interface Name	Content	Definition Header
	CRCD	SFR (CRC data register)	sfr64.h
	CRCIN	SFR (CRC input register)	sfr64.h
Declaration	void FlashReadSumCalc (FLASH_BLOCK_NUM BlockNum, UWORD *SumValue, UWORD *CrcValue);		
Argument	Type	Meaning	
	FLASH_BLOCK_NUM	The block index number for checksum and CRC calculation in the internal flash memory	
	UWORD *	Buffer pointer for the checksum value	
	UWORD *	Buffer pointer for the CRC value	
Returned Value	Type	Meaning	
	void	None	
Function			
Read data of all specified block areas in the internal flash memory and calculate their checksum values and CRC values.			
Remark			
The checksum value (UWORD *SumValue) and the CRC value (UWORD *CrcValue) should be initialized before this function is called.			

5. Sample Code

Sample code can be downloaded from the Renesas Electronics website.

6. Reference Documents

M16C/63 Group User's Manual: Hardware Rev.2.00
M16C/64 Group User's Manual: Hardware Rev.1.05
M16C/64A Group User's Manual: Hardware Rev.2.00
M16C/64C Group User's Manual: Hardware Rev.1.00
M16C/65 Group User's Manual: Hardware Rev.2.00
M16C/65C Group User's Manual: Hardware Rev.1.00
M16C/6C Group User's Manual: Hardware Rev.2.00
M16C/5LD Group, M16C/56D Group User's Manual: Hardware Rev.1.20
M16C/5L Group, M16C/56 Group User's Manual: Hardware Rev.1.10
M16C/5M Group, M16C/57 Group User's Manual: Hardware Rev.1.10
The latest versions can be downloaded from the Renesas Electronics website.

Technical Update/Technical News
The latest information can be downloaded from the Renesas Electronics website.

C Compiler Manual
M16C Series, R8C Family C Compiler Package V.5.45
C Compiler User's Manual Rev.2.00
The latest version can be downloaded from the Renesas Electronics website.

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Revision History	M16C/63, 64, 64A, 64C, 65, 65C, 6C, 5LD, 56D, 5L, 56, 5M, and 57 Groups Use of User Boot Function

Rev.	Date	Description	
		Page	Summary
1.00	Jan. 22, 2010	—	First edition issued
1.01	Feb. 28. 2011	—	Add: M16C/63, M16C/64C, M16C/65C, M16C/6C, M16C/5LD,
			M16C/56D, M16C/5L, M16C/56, M16C/5M, and M16C/57
1.02	Dec. 28. 2011	1	1. Abstract: Added the sentence “This application note describes the user boot function using the M16C/64 Group”.
		2	3.1 Outline: Added.
		2	3.2 Introduction of User Boot Function: Rewrote the second bullet.
		9	Figure 3.5 Processing of User Boot Mode Selection: Changed “Low-voltage detect reset” to “Voltage monitor reset”.
		12	4.3 Processing Outline: Revised.
		20	Table 4.4 Files Used in the Sample Program: Modified the Outlines for xmodem.c and xmodem.h.
		21	Table 4.5 Module Interfaces: • Modified the Remarks from FDS_OK to FDS_ERASE_FAIL. • Added interfaces LBP_DISABLE and LBP_ENABLE. • Modified the Function for FlashReadSumCalc.
		25	BlockErase function table: • Added arguments LBP_ENABLE and LBP_DISABLE. • Modified the Function.
		27	FlashReadSumCalc function table: Modified the Outline.

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins
   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.
   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.
2. Processing at Power-on
   The state of the product is undefined at the moment when power is supplied.
   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.
3. Prohibition of Access to Reserved Addresses
   Access to reserved addresses is prohibited.
   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.
4. Clock Signals
   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.
   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.
5. Differences between Products
   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.
   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.

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